Preliminary Product Information Sheet

EPO-TEK® 509EBT-M1 (*formerly 78-127*)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date:	September 2017		**Recommended Cure: 60°C / 2 Hours**
Rev:	II		
No. of Components:	Two		Minimum Alternative Cure(s):
Mix Ratio by Weight:	100 : 47		*May not achieve performance properties listed below*
Specific Gravity:	Part A: 1.15	Part B: 1.03	23°C / 24 Hours
Pot Life:	30 Minutes		
Shelf Life- Bulk:	One year at room temperature		

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: Two component, slightly thixotropic epoxy suggested for general adhesive bonding, sealing, potting and encapsulation. Replacement for EPO-TEK® 509EBT-M.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	**Cure condition:** varies as required	
Color (before cure):	Part A: Black	Part B: Amber
Consistency:	Thixotropic paste	
Viscosity (23°C) @ 50 rpm:	6,217	cPs
Thixotropic Index:	3.4	
Glass Transition Temp:	75	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	67	x 10^{-6} in/in°C
Above Tg:	277	x 10^{-6} in/in°C
Shore D Hardness:	82	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	16.3	Kg
Degradation Temp:	327	°C
Weight Loss:		
@ 200°C:	0.07	%
@ 250°C:	0.18	%
@ 300°C:	0.42	%
Suggested Operating Temperature:	< 250	°C (Intermittent)
Storage Modulus:	298,633	psi
Particle Size:	≤ 20	microns

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	< 10% @300-700	nm
Refractive Index:	N/A	

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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